

IN THE CLAIMS

A clean copy of the claims incorporating any amendment is shown below.

Please amend Claims 1, 3, 8, 9, 15, 19 and 20 as follows:

92 1. (Amended) A substrate treatment process for removing organic matter existing on a substrate, comprising treating said substrate with ozone water prepared by dissolving an ozone-containing gas in ultrapure water and hydrogen water prepared by dissolving a hydrogen-containing gas in ultrapure water in tandem.

93 3. (Amended) A substrate treatment process according to claim 1 or 2, wherein said substrate to be treated is one of a glass substrate and a substrate comprising one of silicon crystal and metal compound crystal.

94 8. (Amended) A substrate treatment process according to claim 1, wherein said ozone water is applied to said substrate under treatment at a rate not lower than 1 mL/min per square centimeter of substrate area.

9. (Amended) A substrate treatment process according to claim 1, wherein said hydrogen water is applied to said substrate under treatment after activating said hydrogen water by ultrasonic treatment.

95 15. (Amended) A substrate treatment process according to claim 1, wherein said organic matter is subjected to ashing with an oxidizing gas before the step in which the substrate is treated with one of said ozone water and said hydrogen water.

96 19. (Amended) A substrate treatment process according to claim 1, wherein said substrate is cleaned with an organic solvent before the step in which the substrate is treated with one of said ozone water and said hydrogen water.

20. (Amended) A substrate treatment process according to claim 1, wherein said substrate is treated with HF-containing water after the step in which the substrate is treated